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#### November 2013

## FQP19N20C / FQPF19N20C N-Channel QFET<sup>®</sup> MOSFET

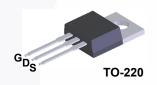
200 V, 19 A, 170 m $\Omega$ 

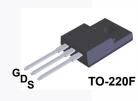
### Features

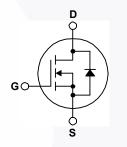
- 19 A, 200 V,  $R_{DS(on)}$  = 170 m $\Omega$  (Max.) @ V\_{GS} = 10 V,  $I_D$  = 9.5 A
- Low Gate Charge (Typ. 40.5 nC)
- Low Crss (Typ. 85 pF)
- 100% Avalanche Tested

## Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.







### MOSFET Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

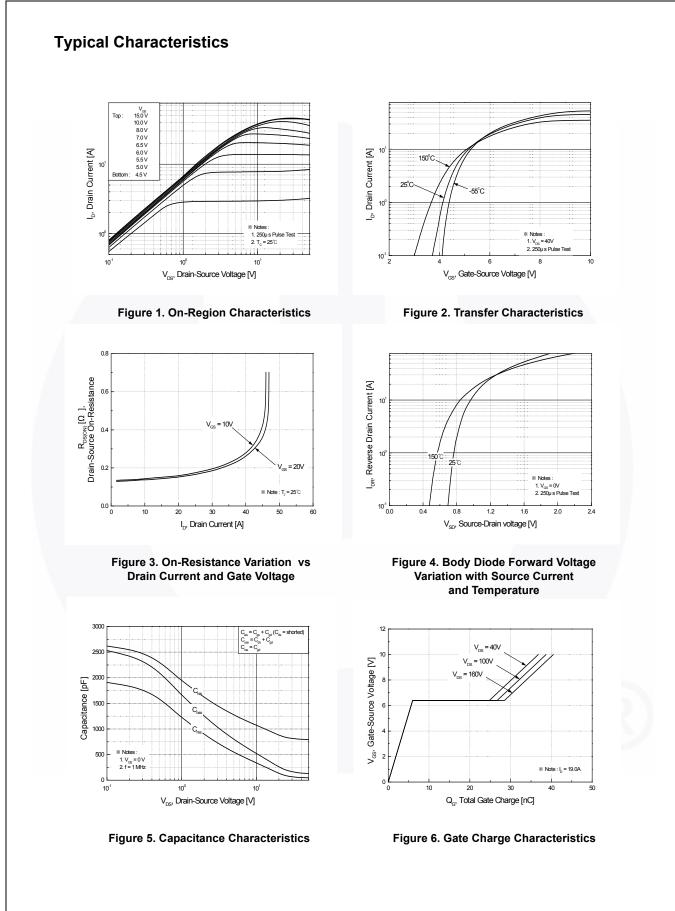
Parameter			FQP19N20C	FQPF19N20C	Unit
Drain to Source Voltage			200		V
Ducia Current	-Continuous (T <sub>C</sub> = 25 <sup>o</sup> C)	-Continuous (T <sub>C</sub> = 25 <sup>o</sup> C) -Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)		19.0 *	А
Drain Current	-Continuous (T <sub>C</sub> = 100 <sup>o</sup> C)			12.1 *	А
Drain Current	- Pulsed	(Note 1)	76.0	76.0 *	А
Gate to Source Voltage	Gate to Source Voltage		± 30		V
Single Pulsed Avalanche Energy		(Note 2)	433		mJ
Avalanche Current		(Note 1)	19.0		А
Repetitive Avalanche Energy		(Note 1)	13.9		mJ
Peak Diode Recovery dv/dt (Not		(Note 3)	5.5		V/ns
Dower Dissinction	(T <sub>C</sub> = 25°C)		139	43	W
Power Dissipation	- Derate above 25°C		1.11	0.34	W/°C
Operating and Storage Temperature Range		-55 to +150		°C	
Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300		°C
	Drain Current   Drain Current   Gate to Source Voltage   Single Pulsed Avalanch   Avalanche Current   Repetitive Avalanche E   Peak Diode Recovery of   Power Dissipation   Operating and Storage   Maximum Lead Temper   1/8" from Case for 5 Set	$\begin{tabular}{ c c c c } \hline Drain to Source Voltage & -Continuous (T_C = 25^\circ C) & -Continuous (T_C = 100^\circ C) & -Pulsed & & & & & & & & & & & & & & & & & & &$	$\begin{tabular}{ c c c c } \hline Drain to Source Voltage & -Continuous (T_C = 25^\circ C) & -Continuous (T_C = 100^\circ C) & -Pulsed & (Note 1) & -Pulsed & (Note 2) & -Pulsed & (Note 2) & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & (Note 2) & -Pulsed & (Note 2) & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & -Pulsed & (Note 2) & -Pulsed & -Pulsed & -Pulsed & (Note 2) & -Pulsed $	$\begin{tabular}{ c c c c c } \hline Drain to Source Voltage & -Continuous (T_C = 25^\circ C) & 19.0 & -Continuous (T_C = 100^\circ C) & 12.1 & 12.$	$\begin{array}{c c c c c c c } \hline \mbox{Drain to Source Voltage} & 200 \\ \hline \mbox{Drain Current} & -Continuous (T_C = 25^{\circ}C) & 19.0 & 19.0 & * \\ -Continuous (T_C = 100^{\circ}C) & 12.1 & 12.1 & * \\ \hline \mbox{Drain Current} & -Pulsed & (Note 1) & 76.0 & 76.0 & * \\ \hline \mbox{Gate to Source Voltage} & & & & & & & & \\ \hline \mbox{Gate to Source Voltage} & & & & & & & & & \\ \hline \mbox{Single Pulsed Avalanche Energy} & (Note 2) & 433 & & & & \\ \hline \mbox{Single Pulsed Avalanche Energy} & (Note 2) & 433 & & & & \\ \hline \mbox{Avalanche Current} & (Note 1) & 19.0 & & & \\ \hline \mbox{Repetitive Avalanche Energy} & (Note 1) & 19.0 & & & \\ \hline \mbox{Repetitive Avalanche Energy} & (Note 1) & 19.0 & & & \\ \hline \mbox{Repetitive Avalanche Energy} & (Note 1) & 13.9 & & & \\ \hline \mbox{Peak Diode Recovery dv/dt} & (Note 3) & & & & & \\ \hline \mbox{Power Dissipation} & & & & & & \\ \hline \mbox{C}_C = 25^{\circ}C) & & & & & & & \\ \hline \mbox{Operating and Storage Temperature Range} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Note 1} & & & & & & \\ \hline \mbox{Avalanche Current} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & & \\ \hline \mbox{Maximum Lead Temperature for Soldering Purpose,} & & & & & & & \\ \hline Maximum Lead Temperatu$

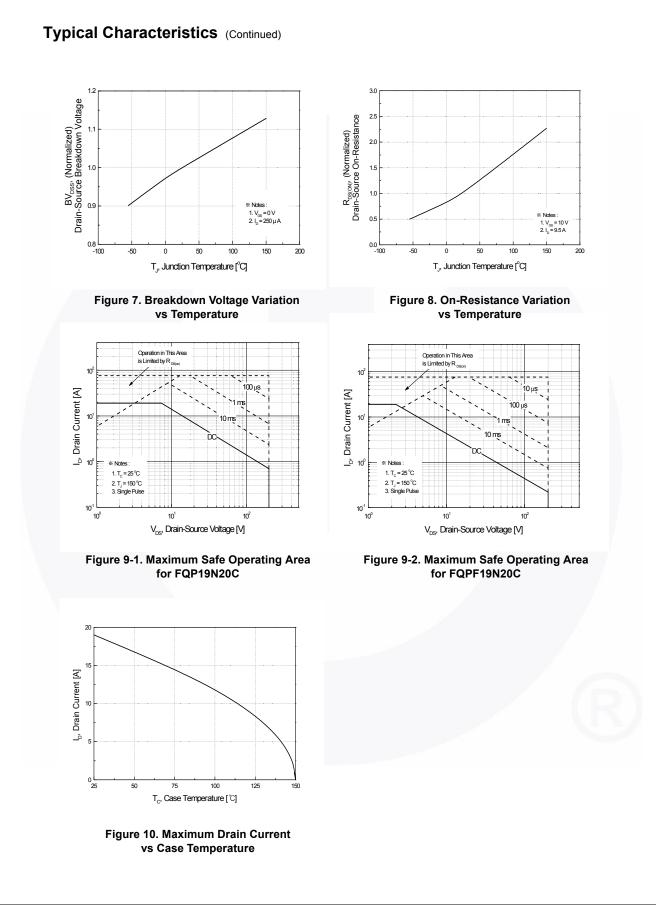
### **Thermal Characteristics**

Symbol	Parameter	FQP19N20C	FQPF19N20C	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	0.9	2.89	°C/W
$R_{ extsf{ heta}JA}$	Thermal Resistance, Junction to Ambient, Max	62.5	62.5	°C/W

Device Marking   Device     FQP19N20C   FQP19N20C     FQPF19N20C   FQPF19N20C		Device	Package	e Re	el Size	Tape Width	Qu	uantity
		TO-220 Tu		Tube	N/A	50	50 units 50 units	
				Tube	N/A	50		
lectri	cal Charact	eristics T <sub>C</sub> = 25°C ur	nless otherwise noted.					
Symbol	1	arameter	Test Condi	tions	Min	Тур	Max	Unit
Off Cha	aracteristics							
BV <sub>DSS</sub>	1	eakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μ	A	200			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coeffi-		$I_D = 250 \mu\text{A}$ , Referenced to 25°C			0.24		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current		V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V				10	μA
			$V_{\rm DS} = 160 \text{ V}, \text{ T}_{\rm C} = 125^{\circ}\text{C}$				100	μA
GSSF	Gate-Body Leak	age Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V	V			100	nA
GSSR	Gate-Body Leak	age Current, Reverse	$V_{GS}$ = -30 V, $V_{DS}$ = 0	V			-100	nA
On Cha	aracteristics							
V <sub>GS(th)</sub>	Gate Threshold	Voltage	$V_{DS} = V_{GS}, I_D = 250$	ιA	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Sou On-Resistance	rce	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 9.5 /	Ą		0.14	0.17	Ω
9fs	Forward Transco	onductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 9.5 A	ł		10.8		S
Dynam	ic Characteris	stice						
C <sub>iss</sub>	Input Capacitan					830	1080	pF
C <sub>oss</sub>	Output Capacita		V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, f = 1.0 MHz			195	255	pF
C <sub>rss</sub>	Reverse Transfe					85	110	pF
								· ·
	ing Character							
t <sub>d(on)</sub>	Turn-On Delay 1		$V_{DD}$ = 100 V, I <sub>D</sub> = 19.0 A, R <sub>G</sub> = 25 Ω			15	40	ns
t <sub>r</sub>	Turn-On Rise Ti					150	310	ns
t <sub>d(off)</sub>	Turn-Off Delay 1					135	280	ns
t <sub>f</sub>	Turn-Off Fall Tin	ne		(Note 4	)	115	240	ns
Qg	Total Gate Char	ge	$V_{DS}$ = 160 V, I <sub>D</sub> = 19.0 A, V <sub>GS</sub> = 10 V			40.5	53.0	nC
Q <sub>gs</sub>	Gate-Source Ch	arge				6.0		nC
Q <sub>gd</sub>	Gate-Drain Char	rge		(Note 4	)	22.5		nC
Drain-9	Source Diode	Characteristics and	l Maximum Rating	10				
l <sub>s</sub>	1	nuous Drain-Source Diode		,5			19.0	А
SM		d Drain-Source Diode For					76.0	A
V <sub>SD</sub>		ode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 19.0 A	4			1.5	V
∙sD t <sub>rr</sub>	Reverse Recover	•	$V_{GS} = 0 V, I_S = 19.0 A$			208		
urr Q <sub>rr</sub>	Reverse Recove		dl <sub>F</sub> / dt = 100 A/μs	<b>x</b> ,		1.63		ns µC
∽m	IVENELSE KECONE	siy charge				1.03		μΟ

4. Essentially independent of operating temperature.





## Typical Characteristics (Continued)

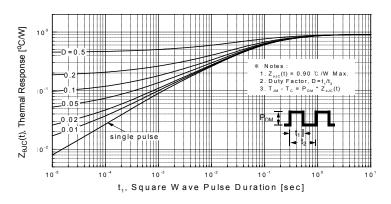
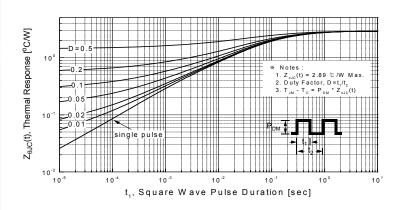
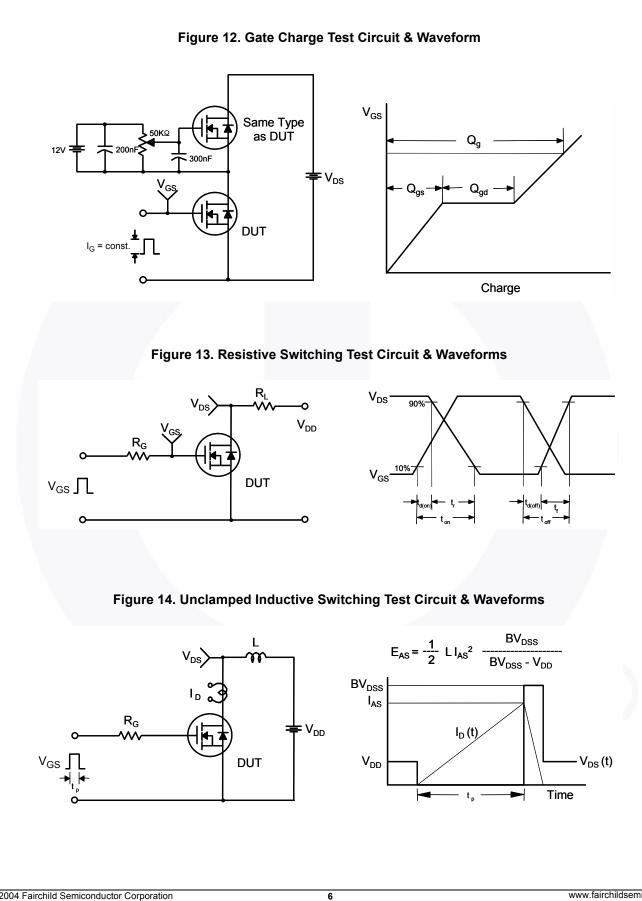


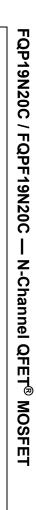
Figure 11-1. Transient Thermal Response Curve for FQP19N20C

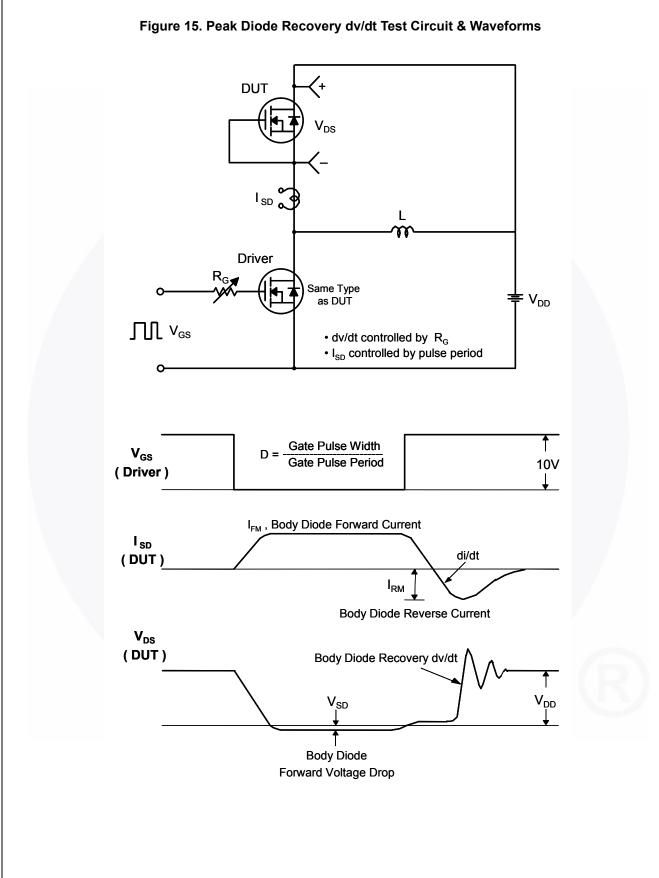


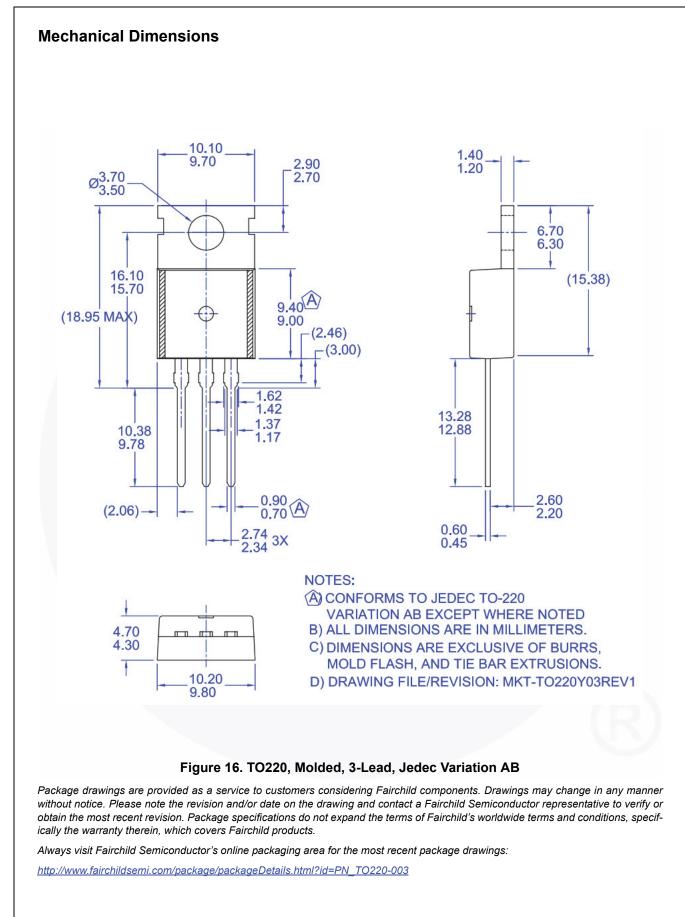


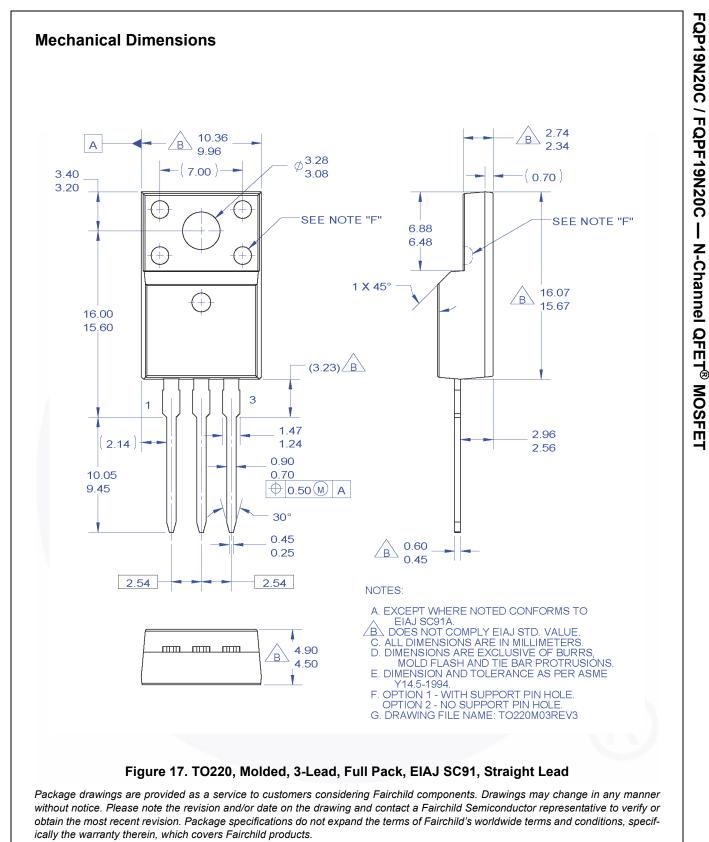


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